

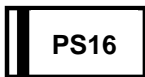
RoHS Compliant Product

A suffix of "-C" specifies halogen-free and RoHS Compliant

FEATURES

- Heatsink Structure
- Low Profile, Typical Thickness 0.8mm
- Moisture Sensitivity: Level 1, Per J-STD-020
- High Temperature Soldering Guaranteed: 260°C/10 Se conds

MARKING



↑
Cathode

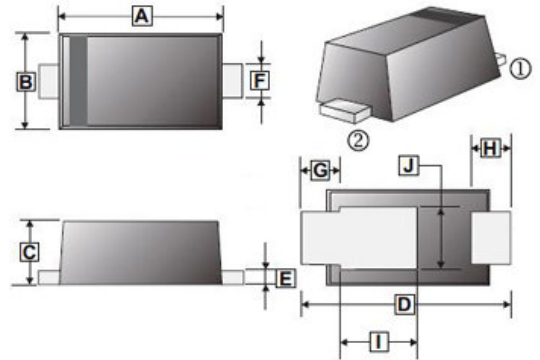
PACKAGE INFORMATION

Package	MPQ	Leader Size
SOD-123DT	3K	7 inch

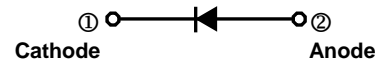
ORDER INFORMATION

Part Number	Type
SM160DT-C	Lead (Pb)-free and Halogen-free

SOD-123DT



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	2.90	3.10	F	0.85	1.05
B	1.90	2.10	G	0.60 REF.	
C	0.75	0.90	H	0.40	0.85
D	3.50	3.90	I	1.66 REF.	
E	0.10	0.25	J	1.30	1.70



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS (T_A=25°C unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	60	V
Maximum RMS Voltage	V _{RMS}	42	V
Maximum DC Blocking Voltage	V _{DC}	60	V
Maximum Average Forward Rectified Current	I _F	1	A
Peak Forward Surge Current @8.3ms single half sine-wave superimposed on rate load	I _{FSM}	30	A
Rating for Fusing (t<8.3ms)	I ² t	3.75	A ² S
Maximum Instantaneous Forward Voltage @I _F =1A	V _F	T _A =25°C	0.65
		T _A =125°C	0.60
Maximum DC Reverse Current @Rated DC Blocking Voltage	I _R	T _A =25°C	50
		T _A =125°C	10
Typical Junction Capacitance ³	C _J	34	pF
Typical Thermal Resistance from Junction-Ambient ¹	R _{θJA}	65	°C/W
Typical Thermal Resistance from Junction-Case ²	R _{θJC}	35	
Typical Thermal Resistance from Junction-Lead ¹	R _{θJL}	9	
Operating Junction & Storage Temperature	T _J , T _{STG}	-55~150	°C

Notes:

1. The thermal resistance from junction to ambient or lead, mounted on P.C.B with 5x5mm copper pads, 2OZ, FR4 PCB.
2. The thermal resistance from junction to case, mounted on P.C.B with recommended copper pads, 2OZ, FR4 PCB.
3. Measured at 1MHz and applied reverse voltage of 4V D.C.

CHARACTERISTIC CURVES

Figure 1. Forward Current Derating Curve

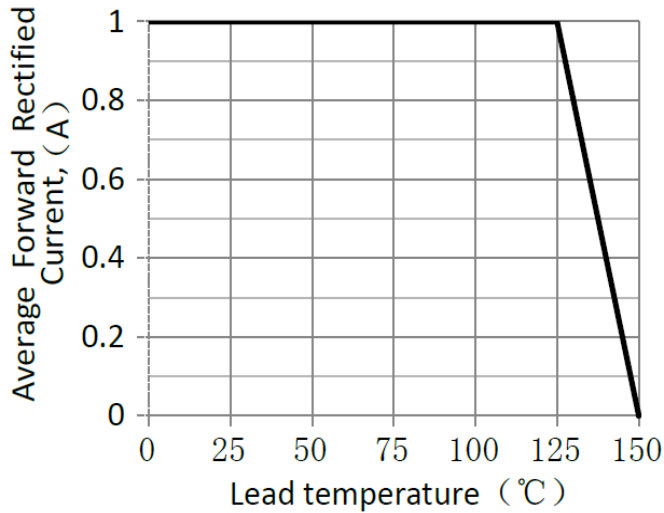


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

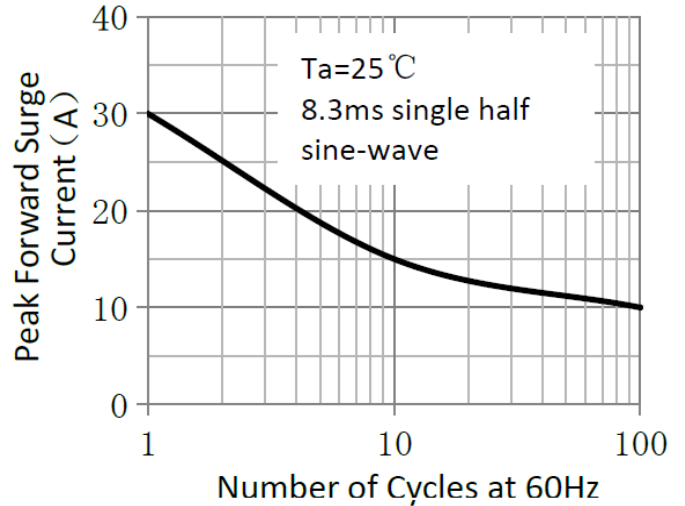


Figure 3. Typical Instantaneous Forward Characteristics

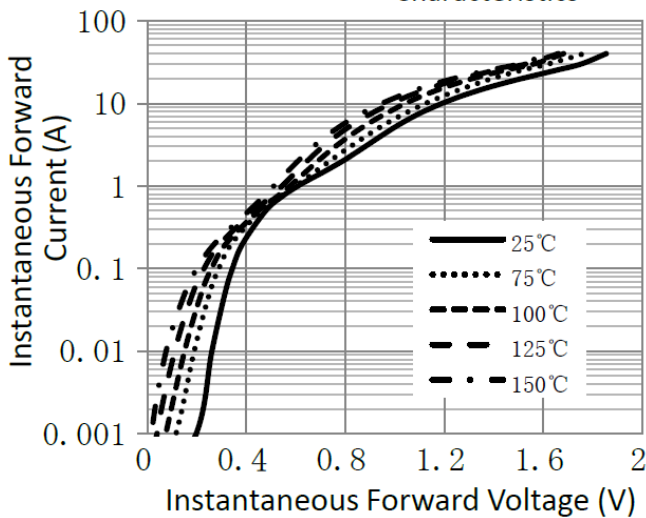


Figure 4. Typical Reverse Characteristics

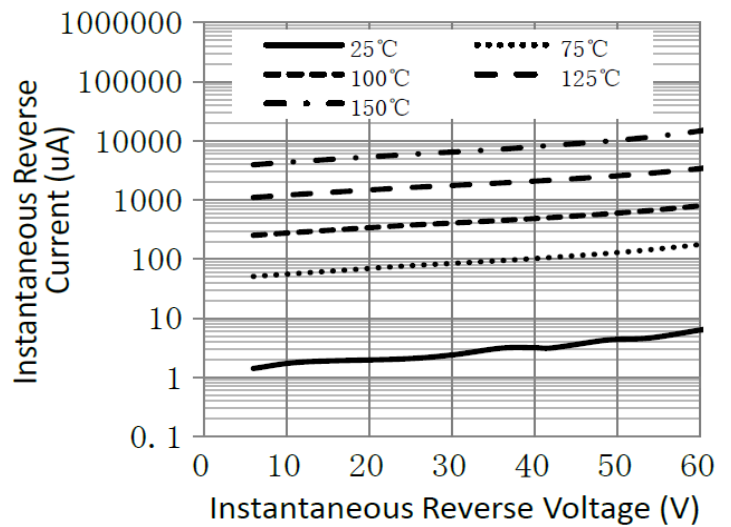


Figure 5. Typical Junction Capacitance

